



October 31, 2007

To: Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Fr: Stephen B. Ackerman, Reg. No. 37,761
28 Davis Avenue
Poughkeepsie, N.Y. 12603

Subject:

Serial No. 09/837,007

4/18/01

M. S. LIN et al

"A Structure and Manufacturing Method of a Chip Scale
Package"

AMENDMENT

Please enter the following amendment, in conjunction with a concurrently filed Petition under 37 CFR 1.78(a)(3) to accept an unintentionally delayed claim for the benefit of a prior-filed application, regarding the above-identified application for patent.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on October 31, 2007.

Stephen B. Ackerman, Reg. No. 37,761

Signature

Date

10/31/07

Amendments to the Specification begin on page 3 of this paper.

Remarks begin on page 4 of this paper.